

Qualification of an Additional Substrate Supplier, SMT Attach Material and Pillar Size Change for LT8650S

Thermal Analysis Summary

PCB:	4L Demo Board				
Device:	LT8650S	T_{ambient} (°C) =			
Die thickness (mm)	Die	P_{loss} (W)	θ_{JA} (K/W)	θ_{JCtop} (K/W)	θ_{JCbot} (K/W)
0.2	U1	3.8	16.18	30.24	4.92
0.45			15.71	18.79	4.45
	Total Power:	3.8			